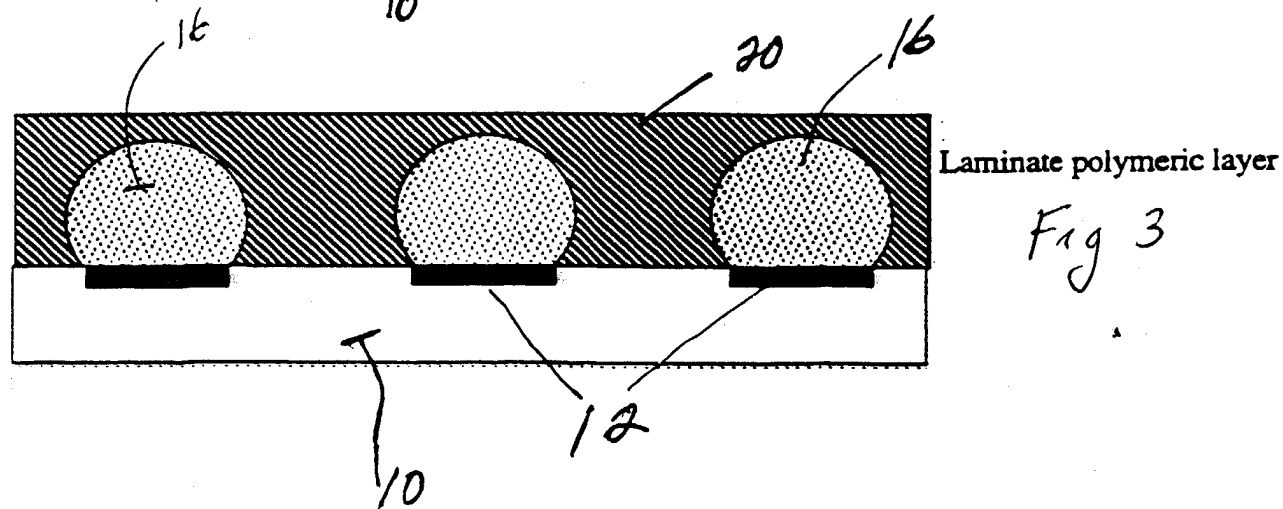
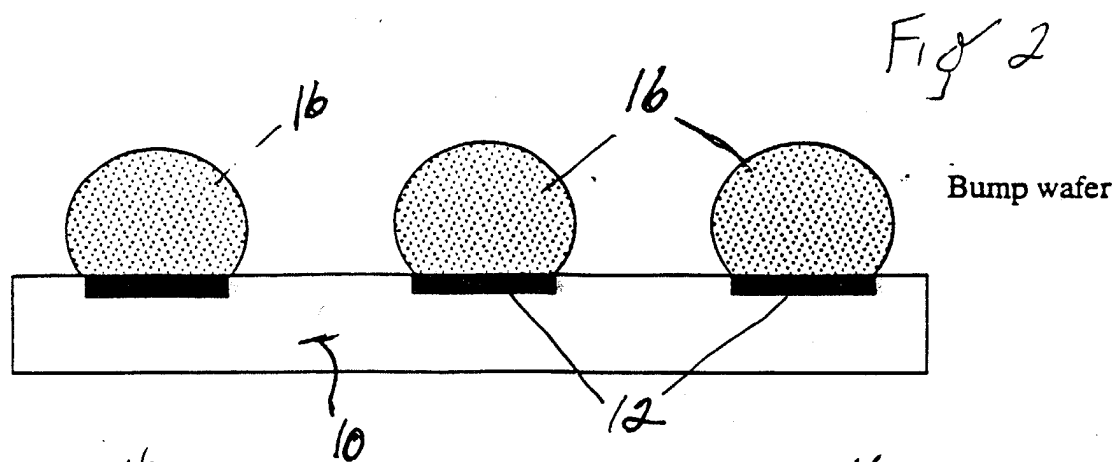
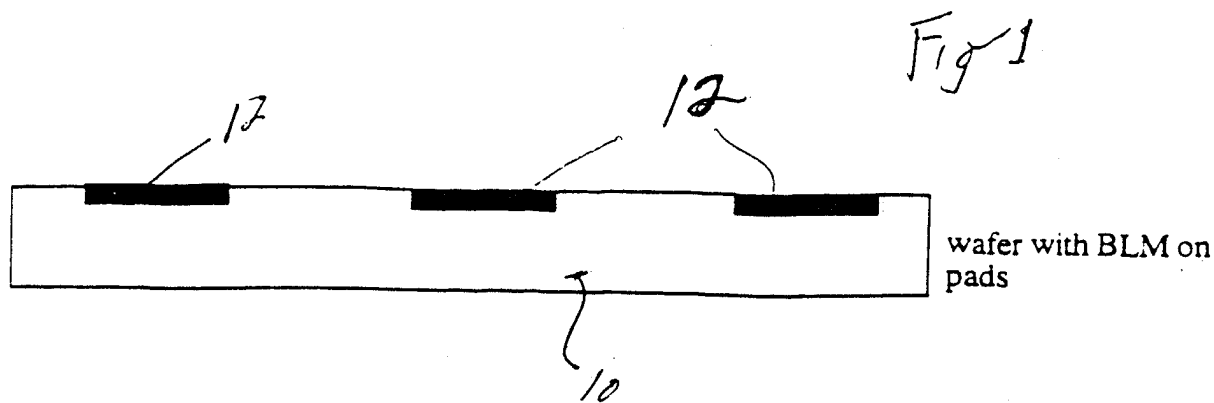
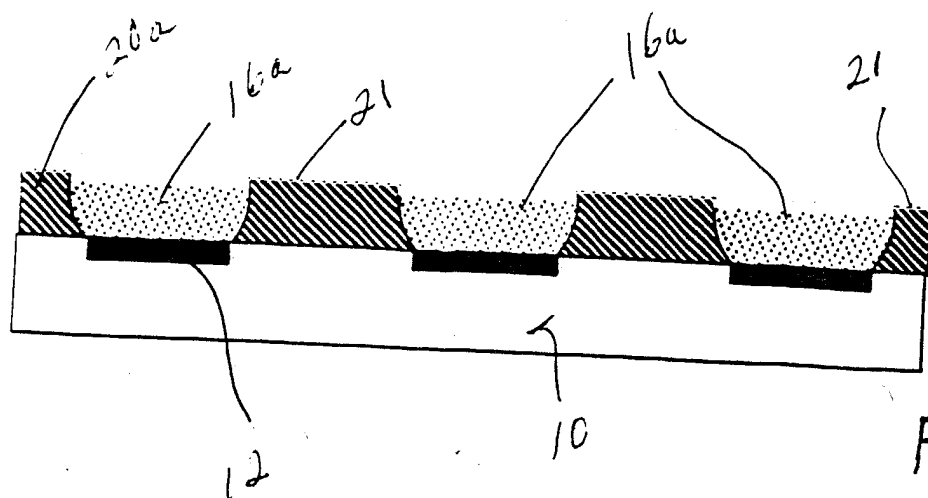


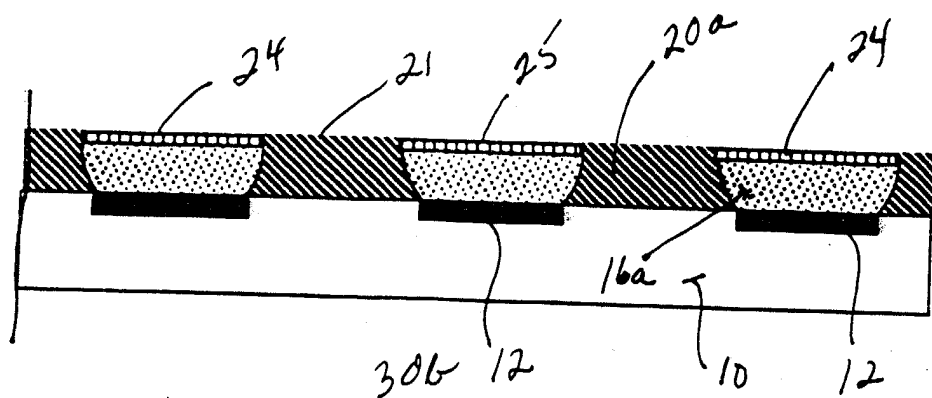
03447-04104





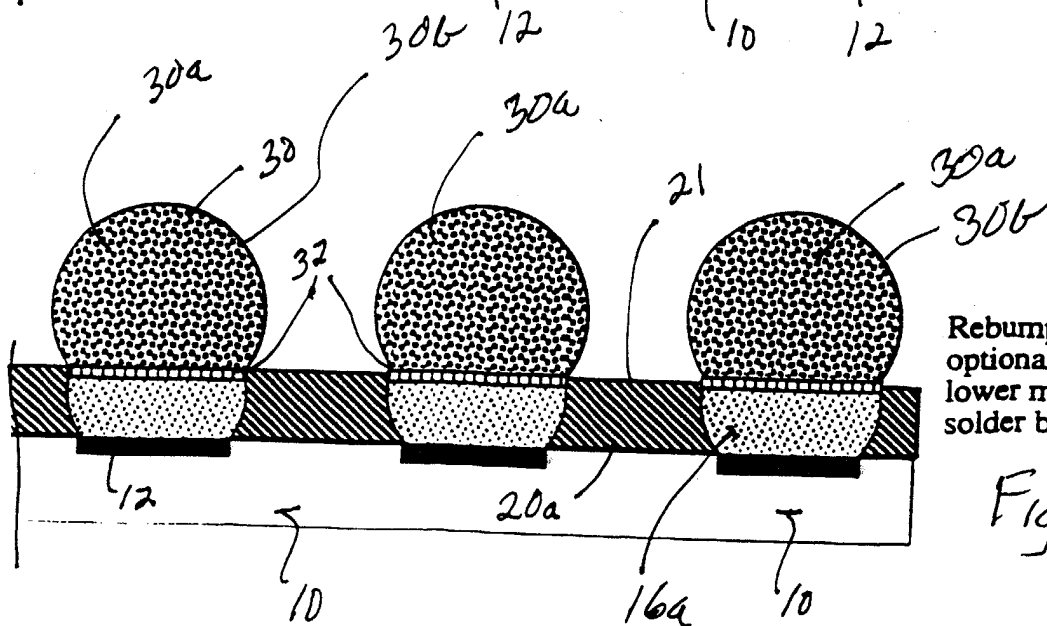
Grind off Polymeric layer to expose bumps, optional light solder etch to remove solder residue from polymeric surface and reduce bump height.

Fig 4A.



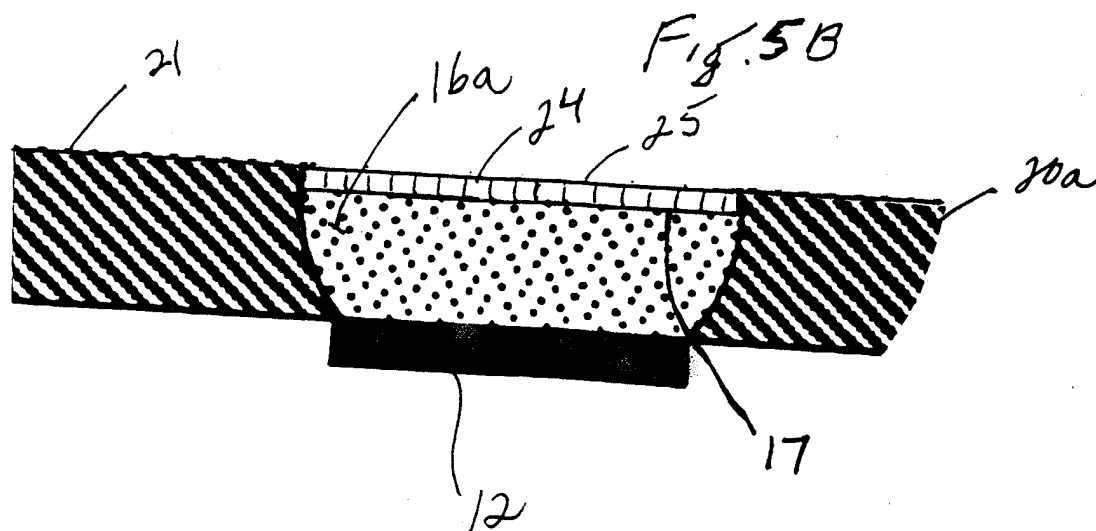
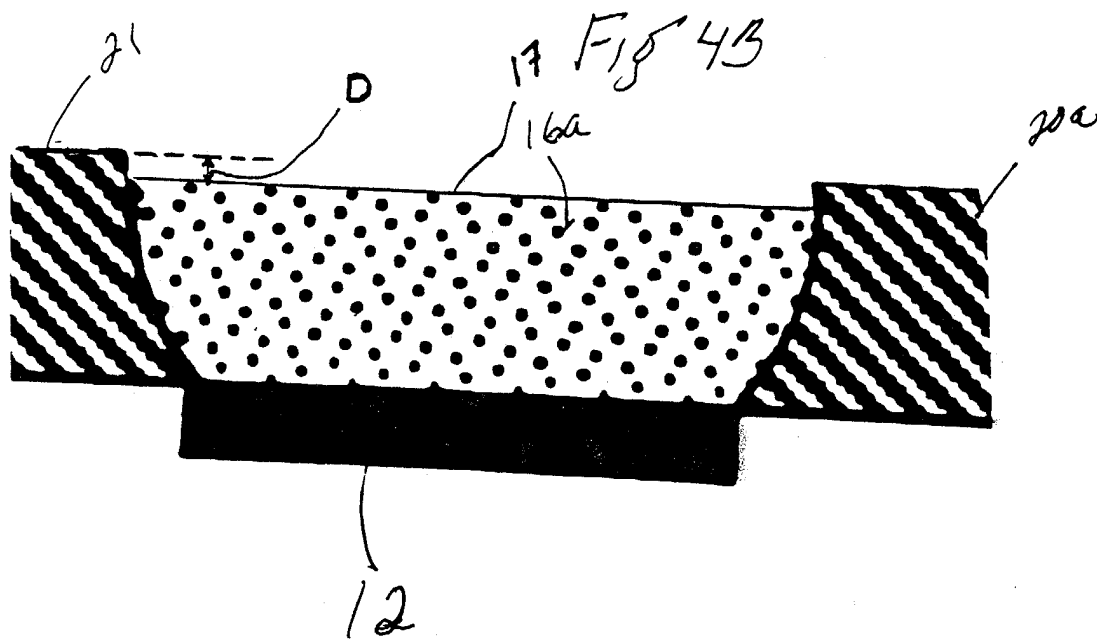
Optional diffusion Barrier deposition

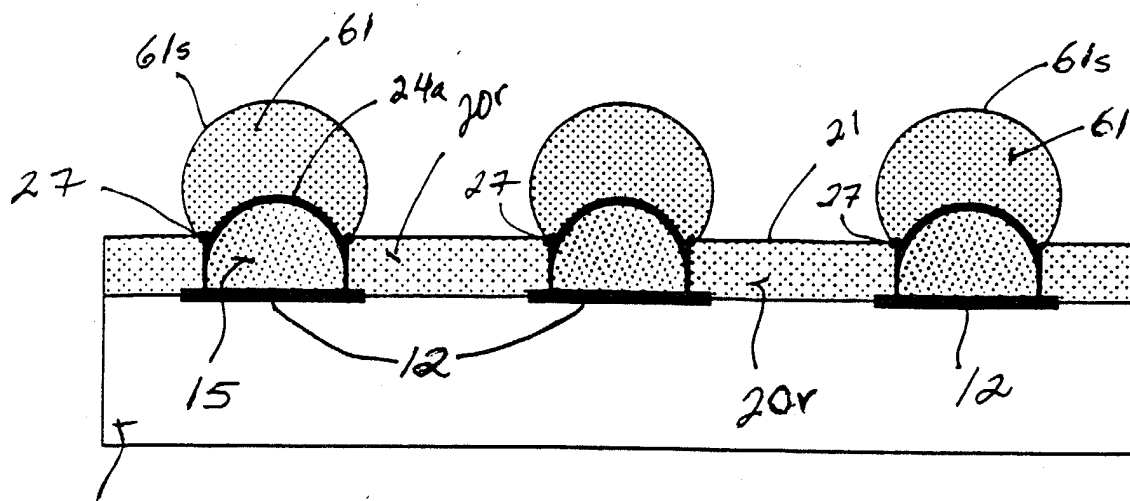
Fig 5A



Rebump : shown with optional barrier layer and lower melting point second solder bumping

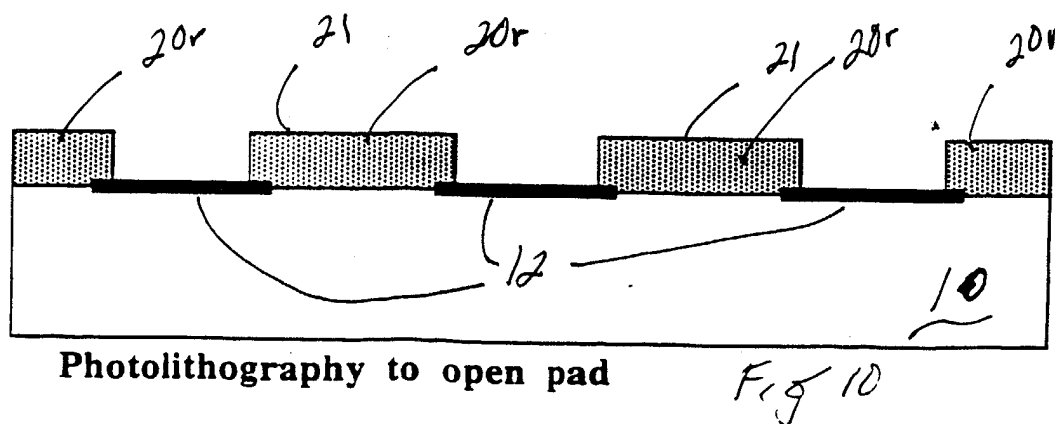
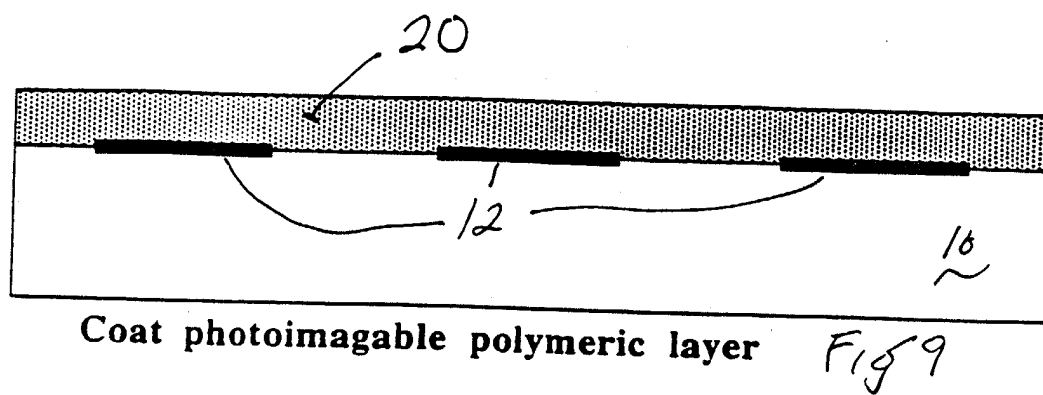
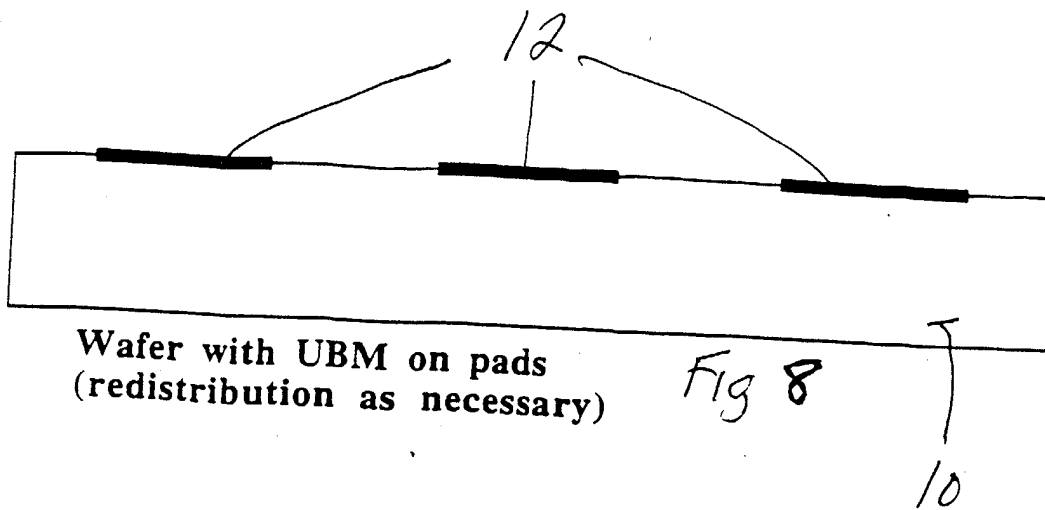
Fig 6

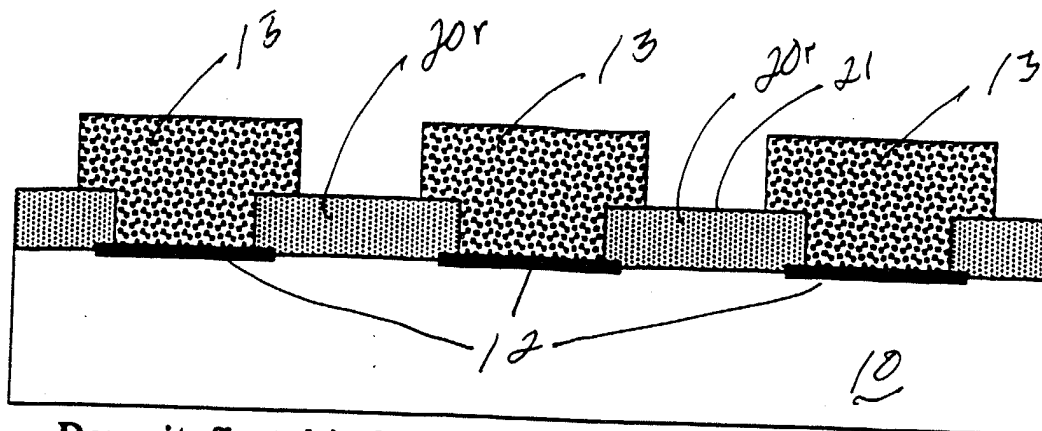




- A wafer bumping structure

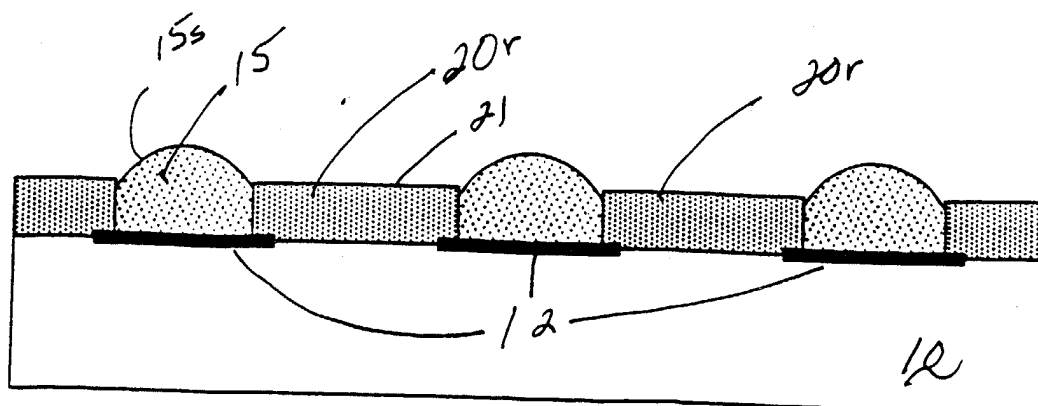
Fig 7





Deposit first kind of solder paste

Fig 11



Reflow wafer to form solder bump
Clean flux residual

Fig 12A

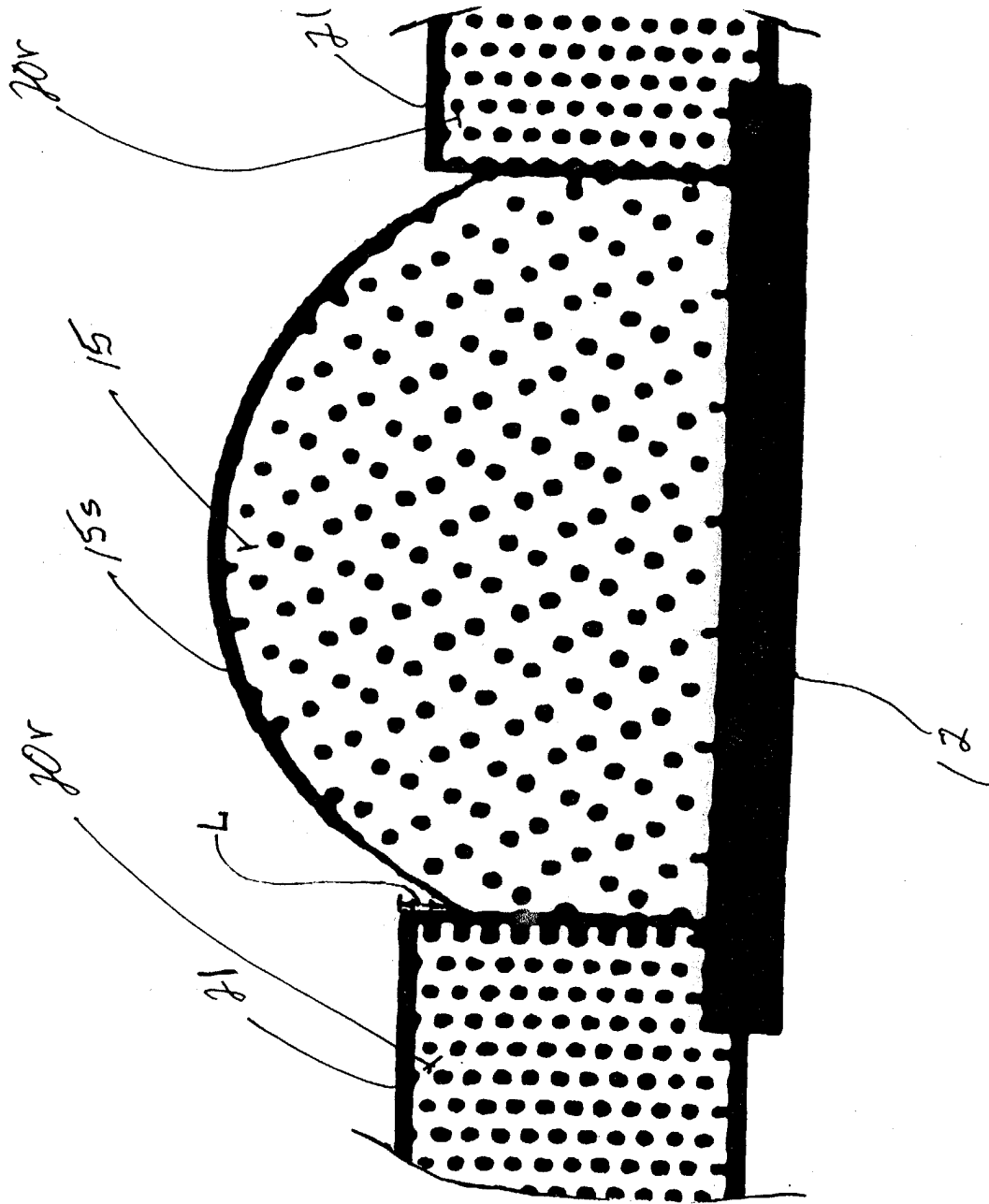


Fig 12B

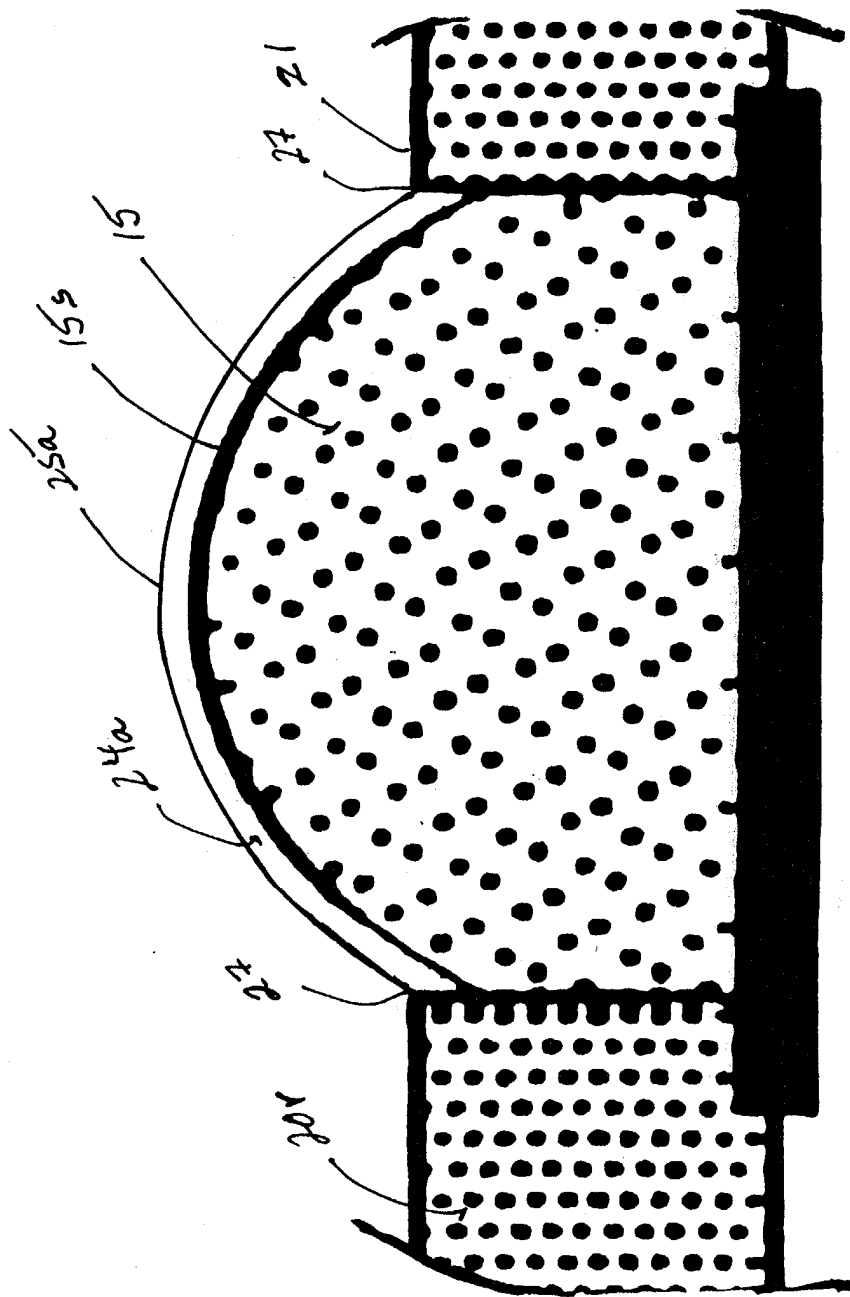
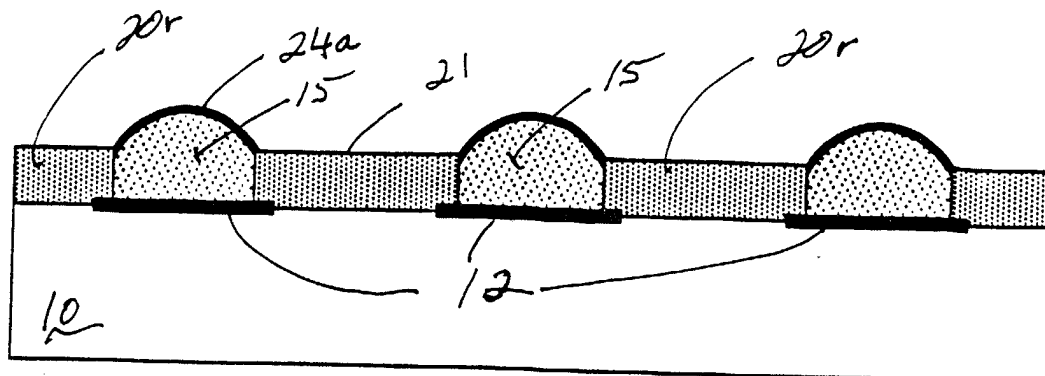
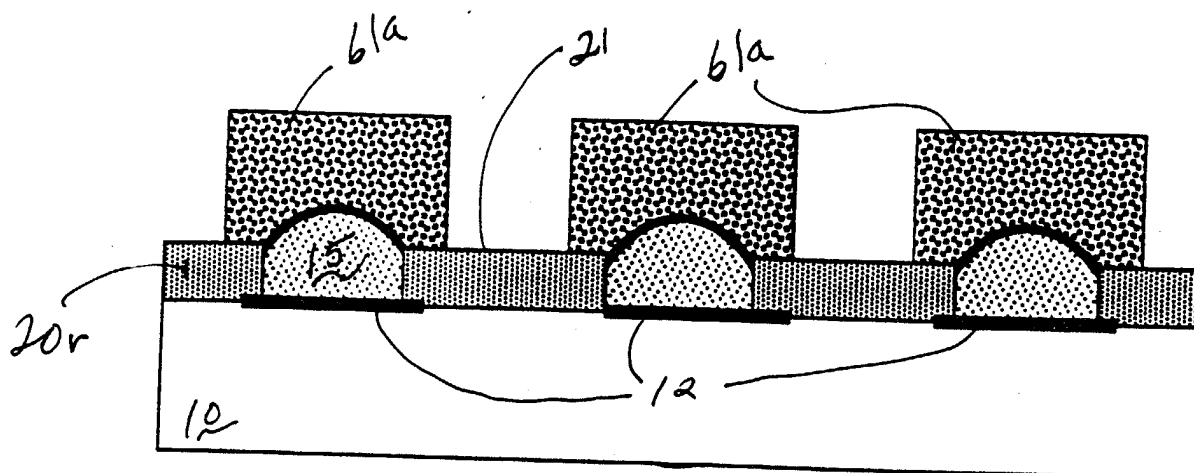


Fig 12C



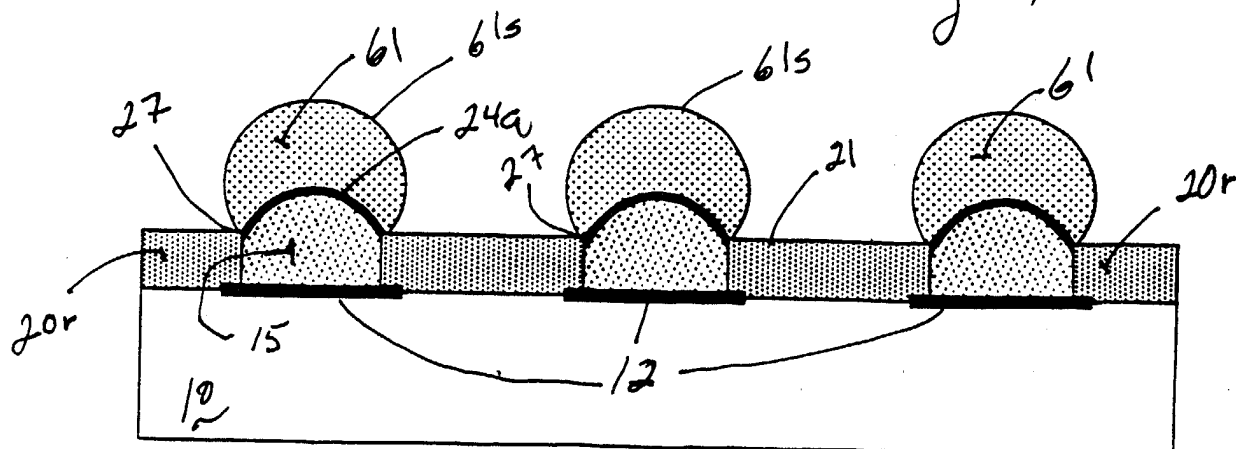
Deposit diffusion barrier

Fig 13



Deposit second kind of solder paste

Fig 14



Reflow wafer to form solder bump
Clean flux residual

Fig 15